

# LMX3305

*LMX3305 Triple Phase Locked Loop for RF Personal Communications*



Literature Number: SNOS533B

## Triple Phase Locked Loop for RF Personal Communications

### General Description

The LMX3305 contains three Phase Locked Loops (PLL) on a single chip. It has a RF PLL, an IF Rx PLL and an IF Tx PLL for CDMA applications. The RF fractional-N PLL uses a 16/17/20/21 quadruple modulus prescaler for PCS application and a 8/9/12/13 quadruple modulus prescaler for cellular application. Both quadruple modulus prescalers offer modulo 1 through 16 fractional compensation circuitry. The RF fractional-N PLL can be programmed to operate from 800 MHz to 1400MHz in cellular band and 1200MHz to 2300 MHz in PCS band. The IF Rx PLL and the IF Tx PLL are integer-N frequency synthesizers that operate from 45 MHz to 600 MHz with 8/9 dual modulus prescalers. Serial data is transferred into the LMX3305 via a microwire interface (Clock, Data, & LE).

The RF PLL provides a fastlock feature allowing the loop bandwidth to be increased by 3X during initial lock-on.

The supply voltage of the LMX3305 ranges from 2.7V to 3.6V. It typically consumes 9 mA of supply current and is packaged in a 24-pin CSP package.

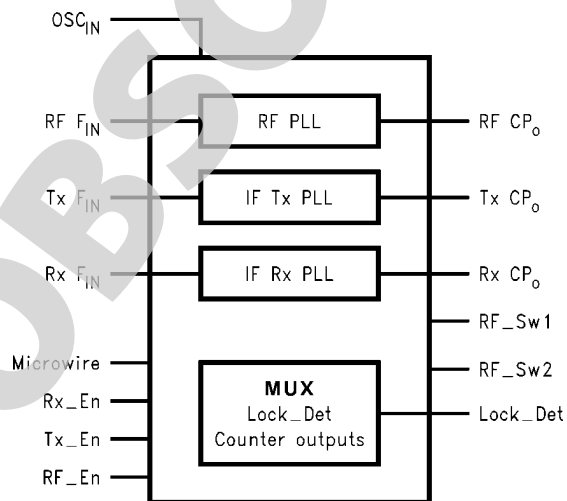
### Features

- Three PLLs integrated on a single chip
- RF PLL fractional-N counter
- 16/17/20/21 RF quadruple modulus prescaler for PCS application
- 8/9/12/13 RF quadruple modulus prescaler for cellular application
- 2.7V to 3.6V operation
- Low current consumption:  $I_{CC} = 9 \text{ mA}$  (typ) at 3.0V
- Programmable or logical power down mode:  $I_{CC} = 10 \mu\text{A}$  (typ) at 3.0V
- RF PLL Fastlock feature with timeout counter
- Digital lock detect
- Microwire Interface with data preset
- 24-pin CSP package

### Applications

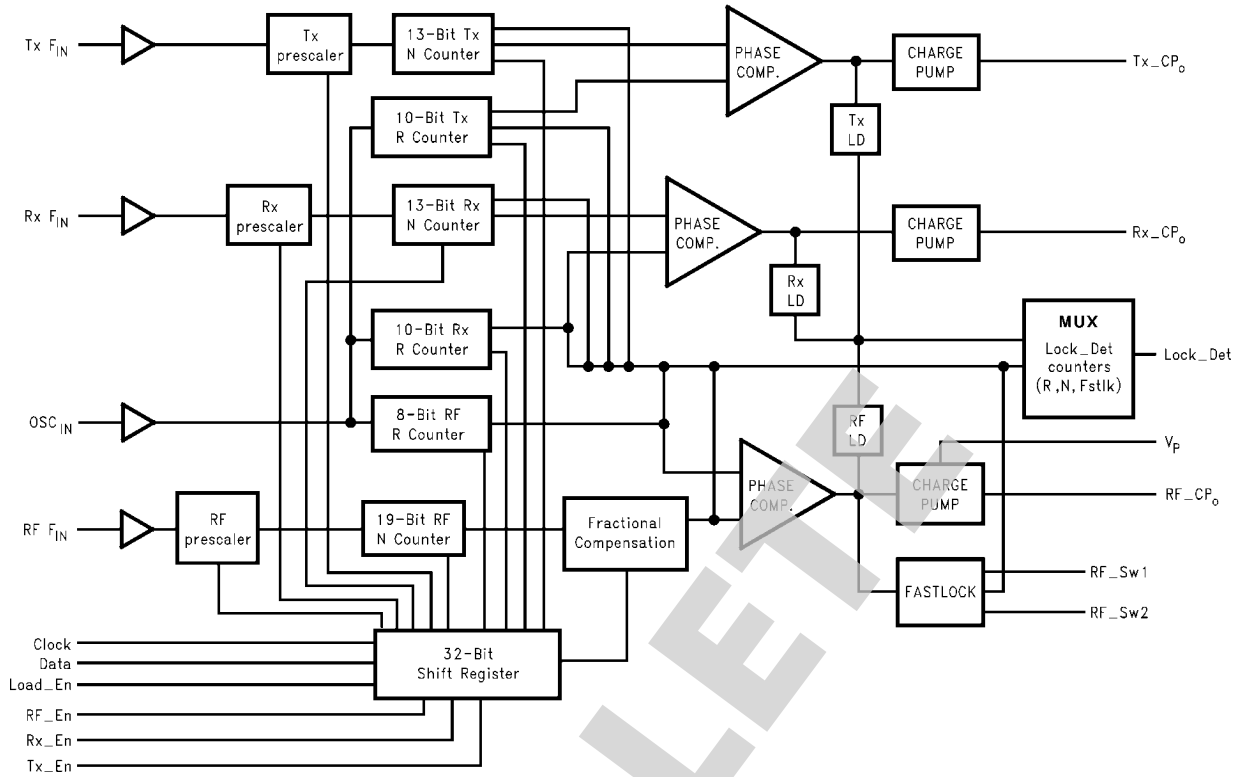
- CDMA Cellular telephone systems

### Block Diagram

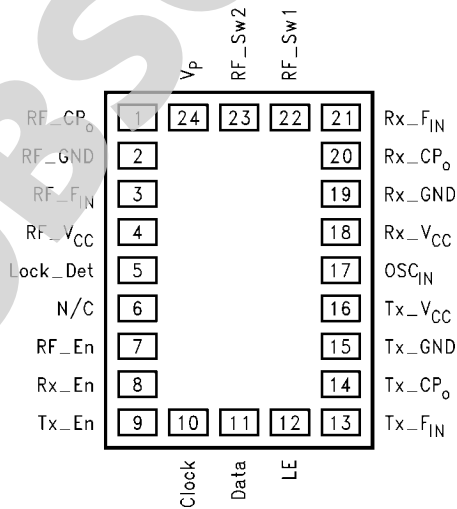


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## Functional Block Diagram



## Connection Diagram



**Top View**  
**Order Number LMX3305SLBX**  
**See NS Package Number SLB24A**

## Pin Descriptions

Pin No.	Pin Name	I/O	Description
1	RF_CP <sub>o</sub>	O	Charge pump output for RF PLL. For connection to a loop filter for driving the input of an external VCO.
2	RF_GND	PWR	RF PLL ground.
3	RF_F <sub>IN</sub>	I	RF prescaler input. Small signal input from the RF Cellular or PCS VCO.
4	RF_V <sub>CC</sub>	PWR	RF PLL power supply voltage. Input may range from 2.7V to 3.6V. Bypass capacitors should be placed as close as possible to this pin and be connected directly to the ground plane. Tx V <sub>CC</sub> = Rx V <sub>CC</sub> = RF V <sub>CC</sub> .
5	Lock_Det	O	Multiplexed output of the RF, Rx, and Tx PLL's analog or digital lock detects. The outputs from the R, N and Fastlock counters can also be selected for test purposes. Refer to Section 2.3.4 for more detail.
6	N/C		No Connect.
7	RF_En	I	RF PLL enable pin. A LOW on RF En powers down the RF PLL and TRI-STATE <sup>®</sup> s the RF PLL charge pump.
8	Rx_En	I	Rx PLL enable pin. A LOW on Rx En powers down the Rx PLL and TRI-STATEs the Rx PLL charge pump.
9	Tx_En	I	Tx PLL enable pin. A LOW on Tx En powers down the Tx PLL and TRI-STATEs the Tx PLL charge pump.
10	Clock	I	High impedance CMOS clock input. Data for the various counters is clocked on the rising edge into the CMOS input.
11	Data	I	Binary serial data input. Data entered MSB first.
12	LE	I	High impedance CMOS input. When LE goes LOW, data is transferred into the shift registers. When LE goes HIGH, data is transferred from the internal registers into the appropriate latches.
13	Tx_F <sub>IN</sub>	I	Tx prescaler input. Small signal input from the Tx VCO.
14	Tx_CP <sub>o</sub>	O	Charge pump output for Tx PLL. For connection to a loop filter for driving the input of an external VCO.
15	Tx_GND		Tx PLL ground.
16	Tx_V <sub>CC</sub>	PWR	Tx PLL power supply voltage input. Input may range from 2.7V to 3.6V. Bypass capacitors should be placed as close as possible to this pin and be connected directly to the ground plane. Tx V <sub>CC</sub> = Rx V <sub>CC</sub> = RF V <sub>CC</sub> .
17	OSC <sub>IN</sub>	I	PLL reference input which has a V <sub>CC</sub> /2 input threshold and can be driven from an external CMOS or TLL logic gate. The R counter is clocked on the falling edge of the OSC <sub>IN</sub> signal.
18	Rx_V <sub>CC</sub>	PWR	Rx PLL power supply voltage. Input ranges from 2.7V to 3.6V. Bypass capacitors should be placed as close as possible to this pin and be connected directly to the ground plane. Tx V <sub>CC</sub> = Rx V <sub>CC</sub> = RF V <sub>CC</sub> .
19	Rx_GND	PWR	Rx PLL ground.
20	Rx_CP <sub>o</sub>	O	Charge pump output for Rx PLL. For connection to a loop filter for driving the input of an external VCO.
21	Rx_F <sub>IN</sub>	I	Rx prescaler input. Small signal input from the Rx VCO.
22	RF_Sw1	O	An open drain NMOS output which can be use for bandswitching or Fastlocking the RF PLL. (During Fastlock mode a second loop filter damping resistor can be switched in parallel with the first to ground.) Refer to Section 2.5.3 for more detail.
23	RF_Sw2	O	An open drain NMOS output which can be use for bandswitching or Fastlocking the RF PLL. (During Fastlock mode a second loop filter damping resistor can be switched in parallel with the first to ground.) Refer to Section 2.5.3 for more detail.
24	V <sub>P</sub>	O	RF PLL charge pump power supply. An internal voltage doubler can be enabled in 3V applications to allow the RF charge pump to operate over a wider tuning range.

**Absolute Maximum Ratings** (Notes 1, 2)

Power Supply Voltage (PLL $V_{CC}$ ) (Note 3)	-0.3V to +6.5V
Supply Voltage ( $V_P$ )	-0.3V to +6.5V
Voltage on any Pin with GND = 0V ( $V_I$ )	-0.3V to $V_{CC}$ +0.3V
Storage Temperature Range ( $T_S$ )	-65°C to +150°C

Lead Temp. (solder, 4 sec.) ( $T_L$ )	+240°C
ESD - Whole Body Model (Note 2)	2 kV

**Recommended Operating Conditions** (Note 1)

Power Supply Voltage (PLL $V_{CC}$ ) (Note 3)	2.7V to 3.6V
Supply Voltage ( $V_P$ ) (Note 3)	PLL $V_{CC}$ to 5.5V
Operating Temperature ( $T_A$ )	-30°C to +85°C

**Electrical Characteristics**(  $V_{CC} = V_P = 3V$ ,  $-30^\circ\text{C} < T_A < 85^\circ\text{C}$  except as specified)

Symbol	Parameter	Conditions	Value			Unit
			Min	Typ	Max	
<b>GENERAL</b>						
$I_{CC}$	Power Supply Current	RF = On, Rx = On, Tx = On $2.7V \leq V_{CC} \leq 3.6V$		9.0	15	mA
$I_{CC-PWDN}$	Power Down Current			10	75	$\mu\text{A}$
$f_{IN}$	PCS Operating Frequency		1200		2300	MHz
	Cellular Operating Frequency		800		1400	
	IF Operating Frequency (Rx, Tx)		45		600	
$f_{OSC}$	Oscillator Frequency			19.68	25	MHz
$f_\phi$	Phase Detector Frequency				10	MHz
$Pf_{IN}$	PCS/Cellular/IF Input Sensitivity	$2.7V \leq V_{CC} \leq 3.6V$	-15		+0	dBm
$Pf_{OSC}$	Oscillator Sensitivity		0.5		$V_{CC}$	$V_{PP}$
RF PN	RF Phase Noise	$F_{OUT} = 1 \text{ GHz}$		-70		dBc/Hz
IF PN	IF Phase Noise			-70		
	Fractional Spur @ 10 kHz	1 kHz Loop Filter (Note 4)			-50	dBc
	Fractional Spur Harmonic		Attenuate 6 dB/OCT after 10 kHz			dBc
Tsw	Switching Speed	1 kHz Loop Filter, 60 MHz Jump to Within 1 kHz			4.0	ms
<b>CHARGE PUMP</b>						
RF $I_{D0}$ Source	RF Charge Pump Source Current	$V_{D0} = V_P/2$ (Note 5)	-22	$I_{NOM}$	22	%
RF $I_{D0}$ Sink	RF Charge Pump Sink Current	$V_{D0} = V_P/2$ (Note 5)	-22	$I_{NOM}$	22	%
IF $I_{D0}$ Source	IF Charge Pump Source Current	$V_{D0} = V_{CC}/2$ (Note 5)	80	100	120	$\mu\text{A}$
IF $I_{D0}$ Sink	IF Charge Pump Sink Current	$V_{D0} = V_{CC}/2$ (Note 5)	-80	-100	-120	$\mu\text{A}$
$I_{D0-TRI}$	Charge Pump TRI-STATE Current	(Note 6)			1000	$\mu\text{A}$
$I_{D0}$ Sink vs $I_{D0}$ Source	Charge Pump Sink vs Source Mismatch	$T_A = 25^\circ\text{C}$ (Note 7)		3	10	%
$I_{D0}$ vs $V_{D0}$	Charge Pump Current vs Voltage	$T_A = 25^\circ\text{C}$ (Note 6)		8	15	%
$I_{D0}$ vs $T_A$	Charge Pump Current vs Temperature	(Note 7)		5	10	%
<b>DIGITAL INPUTS AND OUTPUTS</b>						
$V_{IH}$	High-Level Input Voltage	$V_{CC} = 2.7V$ to $3.6V$	$0.8 V_{CC}$			V
$V_{IL}$	Low-Level Input Voltage	$V_{CC} = 2.7V$ to $3.6V$			$0.2 V_{CC}$	V
$V_{OL}$	Low-Level Output Voltage	$I_{OL} = 2 \text{ mA}$			0.4	V
$I_{IH}$	High-Level Input Current	$V_{IH} = V_{CC} = 3.6V$	-1.0		1.0	$\mu\text{A}$
$I_{IL}$	Low-Level Input Current	$V_{IL} = 0V$ , $V_{CC} = 3.6V$	-1.0		1.0	$\mu\text{A}$
$I_{IH}$	OSC <sub>IN</sub> High-Level Input Current	$V_{IH} = V_{CC} = 3.6V$			100	$\mu\text{A}$

Symbol	Parameter	Conditions	Value			Unit
			Min	Typ	Max	
$I_{IL}$	OSC <sub>IN</sub> Low-Level Input Current	$V_{IL} = 0V, V_{CC} = 3.6V$	-100			$\mu A$
$t_{CS}$	Data to Clock Setup Time		50			ns
$t_{CH}$	Data to Clock Hold Time		10			ns
$t_{CWH}$	Clock Pulse Width High		50			ns
$T_{CWL}$	Clock Pulse Width Low		50			ns
$t_{ENSL}$	Clock to Load_En Setup Time		50			ns
$t_{ENW}$	Load_En Pulse Width		50			ns

**Note 1:** Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Recommended Operating Conditions indicate conditions for which the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics.

**Note 2:** This device is a high performance RF integrated circuit and is ESD sensitive. Handling and assembly of this device should be done on ESD protected workstations.

**Note 3:** PLL  $V_{CC}$  represents RF  $V_{CC}$ , Tx  $V_{CC}$  and Rx  $V_{CC}$  collectively.

**Note 4:** Guaranteed by design. Not tested in production.

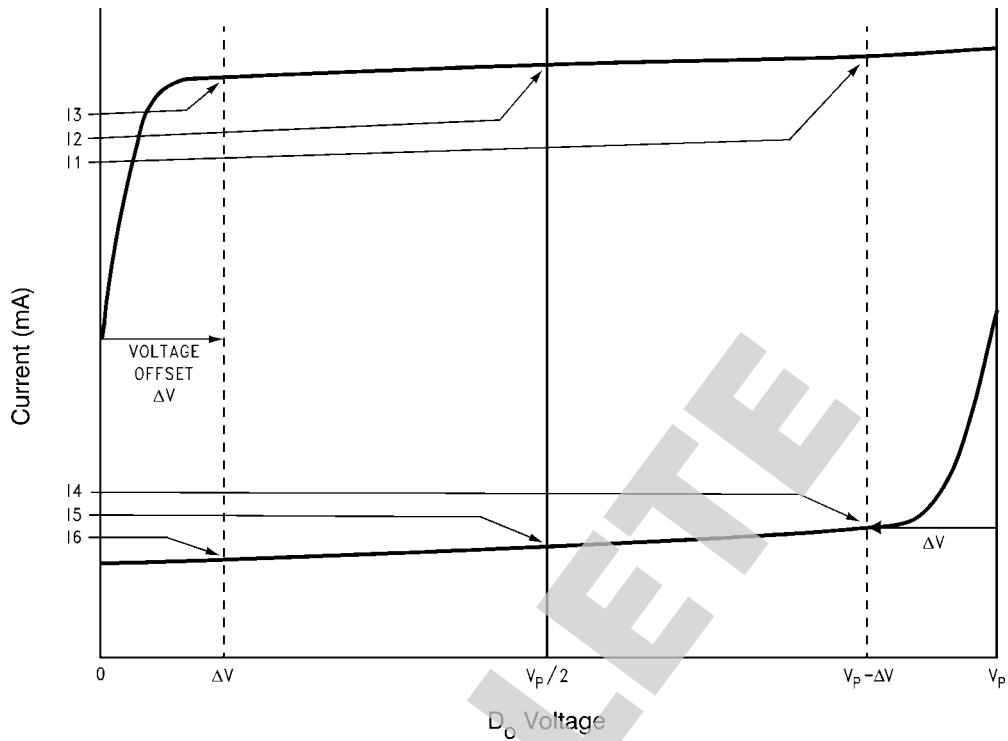
**Note 5:**  $I_{NOM} = 100 \mu A, 400 \mu A, 700 \mu A$  or  $900 \mu A$  for RF charge pump.

**Note 6:** For RF charge pump,  $0.5 \leq V_{D0} \leq V_P - 0.5$ ; for IF charge pump,  $0.5 \leq V_{D0} \leq V_{CC} - 0.5$ .

**Note 7:** For RF charge pump,  $V_{D0} = V_P/2$ , for IF charge pump,  $V_{D0} = V_{CC}/2$ .

OBSOLETE

## Charge Pump Current Specification Definitions



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I1 = CP sink current at  $V_{D_o} = V_p - \Delta V$

I2 = CP sink current at  $V_{D_o} = V_p/2$

I3 = CP sink current at  $V_{D_o} = \Delta V$

I4 = CP source current at  $V_{D_o} = V_p - \Delta V$

I5 = CP source current at  $V_{D_o} = V_p/2$

I6 = CP source current at  $V_{D_o} = \Delta V$

$\Delta V$  = Voltage offset from positive and negative rails. Dependent on VCO tuning range relative to  $V_{CC}$  and ground. Typical values are between 0.5V and 1.0V.

1.  $I_{D_o}$  vs  $V_{D_o}$  = Charge Pump Output Current magnitude variation vs Voltage =

$$\left[ \frac{1}{2} * \{I11 - I13\} \right] / \left[ \frac{1}{2} * \{I11 + I13\} \right] * 100\% \text{ and } \left[ \frac{1}{2} * \{I14 - I16\} \right] / \left[ \frac{1}{2} * \{I14 + I16\} \right] * 100\%$$

2.  $I_{D_o-sink}$  vs  $I_{D_o-source}$  = Charge Pump Output Current Sink vs Source Mismatch =

$$\left[ |I12| - |I15| \right] / \left[ \frac{1}{2} * \{I12 + I15\} \right] * 100\%$$

3.  $I_{D_o}$  vs  $T_A$  = Charge Pump Output Current magnitude variation vs Temperature =

$$\left[ |I12 @ temp1| - |I12 @ 25^\circ C| \right] / |I12 @ 25^\circ C| * 100\% \text{ and } \left[ |I15 @ temp1| - |I15 @ 25^\circ C| \right] / |I15 @ 25^\circ C| * 100\%$$

## 1.0 Functional Description

The LMX3305 phase-lock-loop (PLL) system configuration consists of a high-stability crystal reference oscillator, three frequency synthesizers, three voltage controlled oscillators (VCO), and three passive loop filters. Each of the frequency synthesizers includes a phase detector, a current mode charge pump, as well as programmable reference [R] and feedback [N] frequency dividers. The VCO frequency is established by dividing the crystal reference signal down via the R-counter to obtain a comparison reference frequency. This reference signal ( $f_R$ ) is then presented to the input of a phase/frequency detector and compared with the feedback signal ( $f_N$ ), which is obtained by dividing the VCO frequency down by way of the N-counter, and fractional circuitry. The phase/frequency detector's current source output pumps charge into the loop filter, which then converts the charge into the VCO's control voltage. The function of phase/frequency comparator is to adjust the voltage presented to the VCO until the feedback signal frequency and phase match that of the reference signal. When the RF PLL is in a "Phase-Locked" condition, the RF VCO frequency will be  $(N + F)$  times that of the comparison frequency, where N is the integer divide ratio, and F is the fractional component. The fractional synthesis allows the phase detector frequency to be increased while maintaining the same frequency step size for channel selection. The divider ratio N is thereby reduced giving a lower phase noise referred to the phase detector input, and the comparison frequency is increased allowing faster switching time.

### 1.1 REFERENCE OSCILLATOR INPUTS

The reference oscillator frequency for the RF and IF PLLs are provided from the external references through the  $OSC_{IN}$  pin.  $OSC_{IN}$  input can operate up to 25 MHz with input sensitivity of  $0.5 V_{PP}$  minimum and it drives RF, Rx and Tx R-counters.  $OSC_{IN}$  input has a  $V_{CC}/2$  input threshold that can be driven from an external CMOS or TTL logic gate. Typically, the  $OSC_{IN}$  is connected to the output of a crystal oscillator.

### 1.2 REFERENCE DIVIDERS (R-COUNTERS)

The RF, Rx and Tx R-counters are clocked through the oscillator block. The maximum frequency is 25 MHz. All RF, Rx and Tx R-counters are CMOS design. The RF R-counter is 8-bit in length with programmable divider ratio from 2 to 255. The Rx and Tx R-counters are 10-bit in length with programmable divider ratio from 2 to 1023.

### 1.3 PRESCALERS

The LMX3305 has a 16/17/20/21 quadruple modulus prescaler for the PCS application and a 8/9/12/13 quadruple modulus prescaler for the cellular application. The Rx and Tx prescalers are dual modulus with 8/9 modulus ratio. Both RF/IF prescalers' outputs drive the subsequent CMOS flip-flop chain comprising the programmable N feedback counters.

### 1.4 FEEDBACK DIVIDERS (N-COUNTERS)

The RF, Rx and Tx N-counters are clocked by the output of RF, Rx and Tx prescalers respectively. The RF N-counter is composed of two parts: the 15 MSB bits comprise the integer portion and the 4 LSB bits comprise the fractional portion. The RF fractional N divider is fully programmable from 80 to 32767 over the frequency range from 1200 MHz-2300 MHz for PCS application and 40 to 16383 over the frequency range from 800 MHz-1400 MHz for cellular application. The 4-bit fractional portion of the RF counter represents the fraction's numerator. The fraction's denominator base is determined by the four **FRAC\_D** register bits.

The Rx and Tx N-counters are each a 13-bit integer divisor, fully programmable from 56 to 8,191 over the frequency range from 45 MHz-600 MHz. The Rx and Tx N-counters do not include fractional compensation.

### 1.5 FRACTIONAL COMPENSATION

The fractional compensation circuitry of the LMX3305 RF divider allows the user to adjust the VCO tuning resolution in 1/2 through 1/16th increments of the phase detector comparison frequency. A 4-bit denominator register (**FRAC\_D**) selects the fractional modulo base. The integer averaging is accomplished by using a 4-bit accumulator. A variable phase delay stage compensates for the accumulated integer phase error, minimizes the charge pump duty cycle and reduces the spurious levels. This technique eliminates the need for compensation current injection into the loop filter. An overflow signal generated by the accumulator is equivalent to one full RF VCO cycle, and results in a pulse swallow.

### 1.6 PHASE/FREQUENCY DETECTORS

The RF and IF phase/frequency detectors are driven from their respective N- and R-counter outputs. The maximum frequency at the phase detector inputs is 10 MHz unless limited by the minimum continuous divide ratio of the multi-modulus prescaler. The phase detector output controls the charge pump. The polarity of the pump-up or pump-down control is programmed using **RF\_PD\_POL**, **Rx\_PD\_POL**, or **Tx\_PD\_POL** depending on whether RF or IF VCO characteristics are positive or negative. The phase detector also receives a feedback signal from the charge pump in order to eliminate dead zones.

### 1.7 CHARGE PUMPS

The phase detector's current source output pumps charge into an external loop filter, which then converts it into the VCO's control voltage. The charge pump steers the charge pump output  $CP_o$  to  $V_{CC}$  (pump-up) or Ground (pump-down). When locked,  $CP_o$  is primarily in a TRI-STATE mode with small corrections. The IF charge pump output current magnitudes are nominally 100  $\mu A$ . The RF charge pump output currents can be programmed by the **RF\_Icpo** bits at 100  $\mu A$ , 400  $\mu A$ , 700  $\mu A$ , or 900  $\mu A$ .

### 1.8 VOLTAGE DOUBLER ( $V_P$ )

The  $V_P$  pin is normally driven from an external power supply over a range of  $V_{CC}$  to 5.5V to provide current for the RF charge pump circuit. An internal voltage doubler circuit connected between the  $V_{CC}$  and  $V_P$  supply pins alternately allows  $V_{CC} = 3V (\pm 10\%)$  users to run the RF charge pump circuit at close to twice the  $V_{CC}$  power supply voltage. The voltage doubler mode is enabled by setting the **V2X** bit to a HIGH level. The voltage doubler's charge pump driver originates from the oscillator input. The device will not totally powerdown until the **V2X** bit is programmed LOW. The average delivery current of the doubler is less than the instantaneous current demand of the RF charge pump when active and is thus not capable of sustaining a continuous out of lock condition. A large external capacitor connected to  $V_P$  ( $\approx 0.1 \mu F$ ) is needed to control power supply droop when changing frequencies.

### 1.9 MICROWIRE INTERFACE

The programmable register set is accessed through the microwire serial interface. The interface is comprised of three signal pins: Clock, Data, and LE. After the LE goes LOW, serial data is clocked into the 32-bit shift register upon the rising edge of Clock MSB first. The last three data bits shifted into the shift register select one of five addresses. When LE goes



HIGH, data is transferred from the shift registers into one of the four register bank latches. Selecting the address <000> presets the data in the four register banks. The synthesizer can be programmed even in the power down (or not enabled) state.

### 1.10 LOCK DETECT OUTPUTS

The open-drain Lock Detect is available in the LMX3305 to provide a digital or analog lock detect indication for the sum of the active PLLs. In the digital lock detect mode, an internal digital filter produces a logic level HIGH at the lock detect output when the error between the phase detector inputs is less than 15 ns for five consecutive comparison cycles. The lock detect output is LOW when the error between the phase detector inputs is more than 30 ns for one comparison cycle. In the analog lock detect mode, the lock detect pin becomes active low whenever any of the active PLLs are charge pumping. The **Lock\_Det** pin can also be programmed to provide the outputs of the R, N or fastlock timeout counters.

### 1.11 POWER CONTROL

Each PLL is individually power controlled by the microwire power down bits **Rx\_PWDN**, **Tx\_PWDN** and **RF\_PWDN**. Alternatively, the PLLs can also be power controlled by the **Tx\_En**, **Rx\_En**, and **RF\_En** pins. The enable pins override the power down bits except for the **V2X** bit. When the respective PLL's enable pin is high, the power down bits determine the state of power control. Activation of any PLL power down modes result in the disabling of the respective N counter and de-biasing of its respective  $f_{IN}$  input (to a high impedance state). The R counter functionality also becomes disabled when the power down bit is activated. The reference oscillator block powers down and the **OSC<sub>IN</sub>** pin reverts to a high impedance state when all of the enable pins are LOW or all of the power down bits are programmed HIGH, unless **V2X** bit is HIGH. Power down forces the respective charge pump and phase comparator logic to a TRI-STATE condition. A power down counter reset function resets both N and R counters of the respective PLL. Upon powering up the N counter resumes counting in "close" alignment with the R counter (the maximum error is one prescaler cycle). The microwire control register remains active and capable of loading and latching in data during all of the power down modes.

## 2.0 Programming Description







### 2.3.1 10-Bit IF Programming Reference Divider Ratio (Tx R Counter, Rx R Counter)

Divide Ratio	Tx_R_CNTR [9:0] or Rx_R_CNTR [9:0]										
2	0	0	0	0	0	0	0	0	0	1	0
3	0	0	0	0	0	0	0	0	0	1	1
.	.	.	.	.	.	.	.	.	.	.	.
1023	1	1	1	1	1	1	1	1	1	1	1

**Note:** Divide ratio for both Tx and Rx R counters are from 2 to 1023.

### 2.3.2 Tx\_PD\_POL (IF\_R[18])

This bit sets the polarity of the Tx phase detector. It is set to one when Tx VCO characteristics are positive. When Tx VCO frequency decreases with increasing control voltage, Tx\_PD\_POL should be set to zero.

### 2.3.3 Tx\_RST (IF\_R[17])

This bit will reset the Tx R and N counters when it is set to one. For normal operation, Tx\_RST should be set to zero.

### 2.3.4 LD (IF\_R[16]-[13])

The LD pin is a multiplexed output. When in lock detect mode, LD does ANDing function on the active PLLs. The RF fractional test mode is only intended for factory testing.

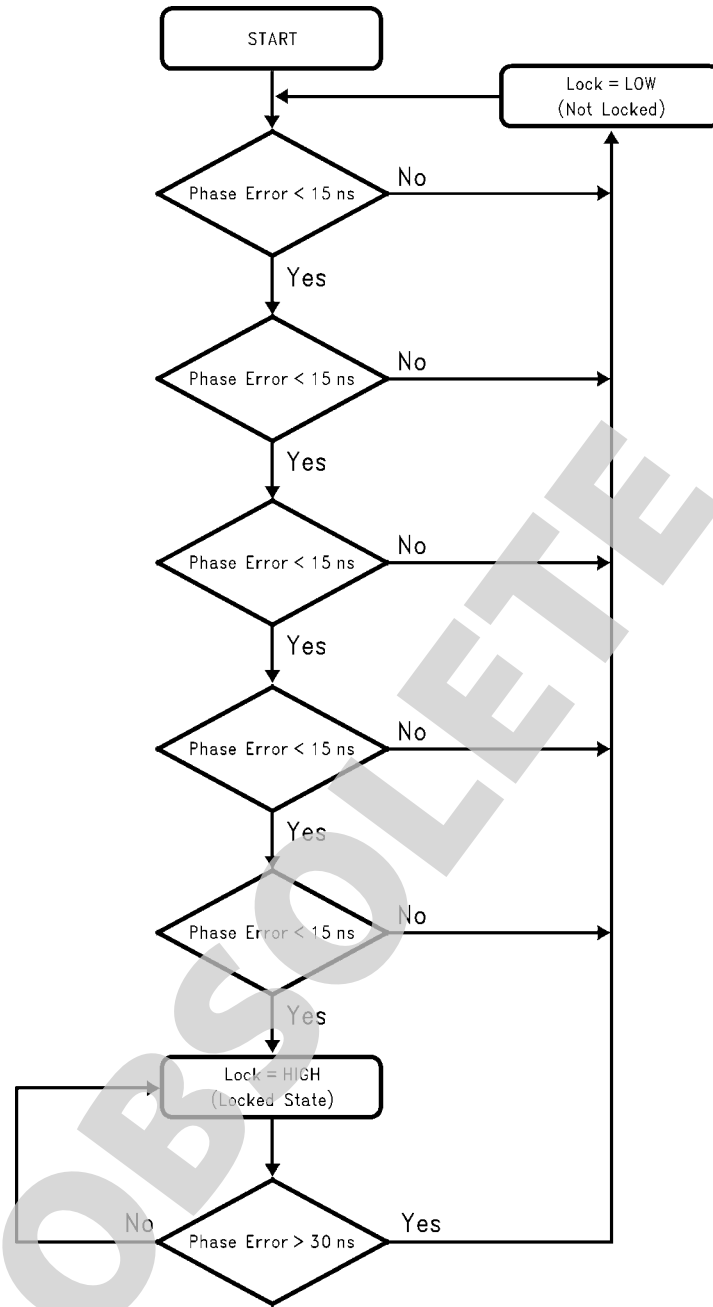
**Lock Detect Output Truth Table**

LD [3:0]				LD Pin Function	Output Format
0	0	0	0	Digital Lock Detect	Open Drain
0	0	0	1	Analog Lock Detect	Open Drain
1	0	0	0	Rx R Counter	CMOS
1	0	0	1	Rx N Counter	CMOS
1	0	1	0	Tx R Counter	CMOS
1	0	1	1	Tx N Counter	CMOS
1	1	0	0	RF R Counter	CMOS
1	1	0	1	RF N Counter	CMOS
1	1	1	0	RF Fastlock Timeout Counter	CMOS
1	1	1	1	RF Fractional Test Mode	Analog

### Lock Detect Digital Filter

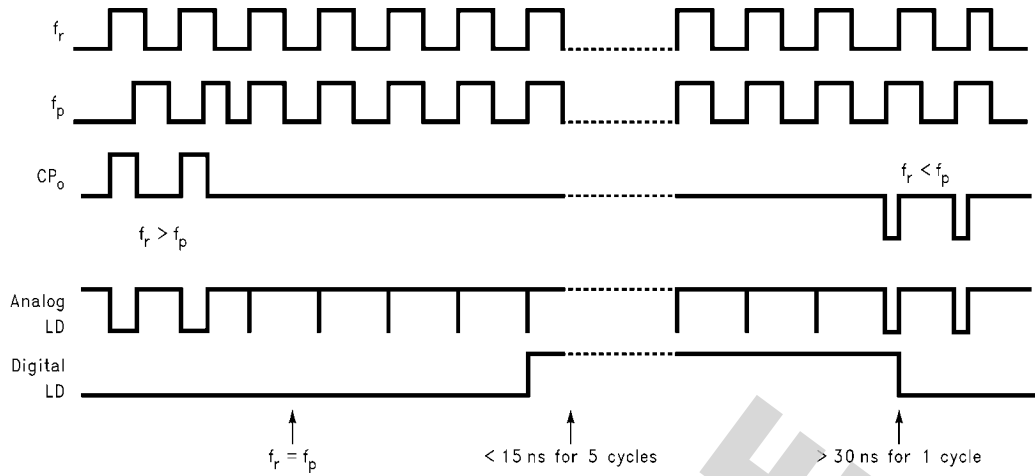
The Lock Detect Digital Filter compares the difference between the phase of the inputs of the phase detector to a RC generated delay of approximately 15 ns. To enter the locked state (Lock Det = HIGH) the phase error must be less than the 15 ns RC delay for five consecutive reference cycles.

Once in lock (Lock Det = HIGH), the RC delay is changed to approximately 30 ns. To exit the locked state (Lock Det = LOW), the phase error must become greater than the 30 ns RC delay. When the PLL is in the powerdown mode, Lock Det is forced HIGH. A flow chart of the digital filter is shown below.



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**Typical Lock Detect Timing**



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**2.3.5 Rx\_PD\_POL (IF\_R[2])**

This bit sets the polarity of the Rx phase detector. It is set to one when Rx VCO characteristics are positive. When Rx VCO frequency decreases with increasing control voltage, Rx\_PD\_POL should set to zero.

**2.3.6 Rx\_RST (IF\_R[1])**

This bit will reset the Rx R and N counters when it is set to one. For normal operation, Rx\_RST should be set to zero.

OBSOLETE





### 2.4.1 3-Bit IF Swallow Counter Divide Ratio (Tx A Counter, Rx A Counter)

Divide Ratio	Tx_NA_CNTR [2:0] or Rx_NA_CNTR [2:0]		
0	0	0	0
1	0	0	1
•	•	•	•
7	1	1	1

Divide ratio is from 0 to 7

$Tx\_NB\_CNTR \geq Tx\_NA\_CNTR$  and  $Rx\_NB\_CNTR \geq Rx\_NA\_CNTR$

### 2.4.2 10-Bit IF Programmable Counter Divide Ratio (Tx B Counter, Rx B Counter)

Divide Ratio	Tx_NB_CNTR [9:0] or Rx_NB_CNTR [9:0]									
3	0	0	0	0	0	0	0	0	1	1
4	0	0	0	0	0	0	0	1	0	0
•	•	•	•	•	•	•	•	•	•	•
1023	1	1	1	1	1	1	1	1	1	1

Divide ratio is from 3 to 1023 (Divide ratios less than 3 are prohibited)

$Tx\_NB\_CNTR \geq Tx\_NA\_CNTR$  and  $Rx\_NB\_CNTR \geq Rx\_NA\_CNTR$

$N = PB + A$

$B = N \text{ div } P$

$A = N \text{ mod } P$

#### 2.4.3 Tx\_PWDN (IF\_N[15])

This bit will asynchronously powerdown the Tx PLL when set to one. For normal operation, it should be set to zero.

#### 2.4.4 Rx\_PWDN (IF\_N[1])

This bit will asynchronously powerdown the Rx PLL when set to one. For normal operation, it should be set to zero.

### 2.5 RF\_R REGISTER

If the ADDRESS [2:0] field is set to 011, data is transferred from the 32-bit shift register into the RF\_R register when LE signal goes high. The RF\_R register sets the RF PLL's 8-bit R counter divide ratio and various programmable bits. The divide ratio for RF R counter is from 2 to 255.

SHIFT REGISTER BIT LOCATION																Least Significant Bit																						
Most Significant Bit																Address Field																						
Data Field																Address Field																						
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0							
RF_R																RF_R_CNTR [7:0]																0						
																RF_R_CNTR [7:0]																0						
RF_R28																RF_R27																1						
RF_R26																RF_R25																1						
RF_R24																RF_R23																1						
RF_R22																RF_R21																1						
RF_R20																RF_R19																1						
RF_R18																RF_R17																1						
RF_R16																RF_R15																1						
RF_R14																RF_R13																1						
RF_R12																RF_R11																1						
RF_R10																RF_R9																1						
RF_R8																RF_R7																1						
RF_R6																RF_R5																1						
RF_R4																RF_R3																1						
RF_R2																RF_PD_POL																1						
RF_R1																RF_RST																1						
RF_R0																V2X																1						

### 2.5.1 8-Bit RF Programming Reference Divider Ratio (RF R Counter)

Divide Ratio	RF_R_CNTR [7:0]							
2	0	0	0	0	0	0	1	0
3	0	0	0	0	0	0	1	1
•	•	•	•	•	•	•	•	•
255	1	1	1	1	1	1	1	1

Divide ratio for RF R counter is from 2 to 255.

### 2.5.2 FSTL\_CNTR (RF\_R[20]-[14])

The Fastlock Timeout Counter is a 10 bit counter wherein only the seven MSB bits are programmable. (The number of phase

detector cycles the fastlock mode remains in HIGH gain is the binary FSTL\_CNTR value loaded multiplied by eight.)

Phase Detect Cycles	FSTL_CNTR [6:0]							
24	0	0	0	0	0	1	1	1
32	0	0	0	0	1	0	0	0
•	•	•	•	•	•	•	•	•
1008	1	1	1	1	1	1	1	0
1016	1	1	1	1	1	1	1	1

### 2.5.3 FSTM (RF\_R[13]-[12]) and FSTSW (RF\_R[11]-[10])

Fastlock enables the designer to achieve both fast frequency transitions and good phase noise performance by dynamically changing the PLL loop bandwidth. The Fastlock modes allow wide band PLL fast locking with seamless transition to a low phase noise narrow band PLL. Consistent gain and phase margins are maintained by simultaneously changing charge pump current magnitude and loop filter damping resistor. In the LMX3305, the RF fastlock can achieve substantial improvement in lock time by increasing the charge pump current by 4X, 7X or 9X, which causes a 2X, 2.6X or 3X increase in the loop bandwidth respectively. The damping resistors are connected to FSTSW pins.

When bit FSTM2 and/or FSTM1 is set HIGH, the RF fastlock is enabled. As a new frequency is loaded, RF\_Sw2 pin and/or RF\_Sw1 pin goes to a LOW state to switch in the damping resistors, the RF CP<sub>o</sub> is set to a higher gain, and fastlock timeout counter starts counting. Once the timeout counter finishes counting, the PLL returns to its normal operation (the lopo gain is forced to 100 μA irrespective of RF\_Icpo bits).

When bit FSTM2 and/or FSTM1 is set LOW, pins RF\_Sw2 and/or RF\_Sw1 can be toggled HIGH or LOW to drive other devices. RF\_Sw2 and/or RF\_Sw1 can also be set LOW to switch in different damping resistors to change the loop filter performance. FSTSW bits control the output states of the RF\_Sw2 and RF\_Sw1 pins.

RF_R[12] FSTM1	RF_R[10] FSTSW1	RF_Sw1 Output Function
0	0	RF_Sw1 pin reflects RF_SwBit "0" logic state
0	1	RF_Sw1 pin reflects RF_SwBit "1" logic state
1	x	RF_Sw1 pin LOW while T.O. counter is active

RF_R[13] FSTM2	RF_R[11] FSTSW2	RF_Sw2 Output Function
0	0	RF_Sw2 pin reflects RF_SwBit "0" logic state
0	1	RF_Sw2 pin reflects RF_SwBit "1" logic state
1	x	RF_Sw2 pin LOW while T.O. counter is active

### 2.5.4 FRAC\_CAL (RF\_R[9]-[5])

These five bits allow the users to optimize the fractional circuitry, therefore reducing the fractional reference spurs. The MSB bit, RF\_R[9], activates the other four calibration bits RF\_R[8]-[5]. These four bits can be adjusted to improve frac-

tional spur. Improvements can be made by selecting the bits to be one greater or less than the denominator value. For example, in the 1/16 fractional mode, these four bits can be programmed to 15 or 17. In normal operation, these bits should be set to zero.

**2.5.5 RF\_Icpo (RF\_R[4]-[3])**

These two bits set the charge pump gain of the RF PLL. The user is able to set the charge pump gain during the acquisition phase of the fastlock mode to 4X, 7X or 9X.

Charge Pump Gain	RF_R[4]	RF_R[3]
100 $\mu$ A	0	0
400 $\mu$ A	0	1
700 $\mu$ A	1	0
900 $\mu$ A	1	1

**2.5.6 RF\_PD\_POL (RF\_R[2])**

This bit sets the polarity of the RF phase detector. It is set to one when RF VCO characteristics are positive. When RF VCO frequency decreases with increasing control voltage, RF\_PD\_POL should be set to zero.

**2.5.7 RF\_RST (RF\_R[1])**

This bit will reset the RF R and N counters when it is set to one. For normal operation, RF\_RST should be set to zero.

**2.5.8 V2X (RF\_R[0])**

V2X when set high enables the voltage doubler for the RF charge pump supply.

OBSOLETE

**2.6 RF\_N REGISTER**

If the ADDRESS [2:0] field is set to 100, data is transferred from the 32-bit shift register into the RF\_N register when LE signal goes high. The RF\_N register set the RF\_PLL's 23-bit fractional N counter and various programmable bits. The fractional N counter consists of 15 bits integer portion and 8 bits fractional portion. The integer portion consists of a 2-bit swallow counter (A word), a 2-bit programmable counter (B word) and a 11-bit programmable counter (C word). The fractional portion consists of a 4-bit numerator and a 4-bit denominator.

SHIFT REGISTER BIT LOCATION															Least Significant Bit																																																																																																																											
															Address Field																																																																																																																											
Data Field																																																																																																																																										
RF_N_CNTR [14:0]															FRAC_N [3:0]				FRAC_D [3:0]				Test [2:0]																																																																																																																			
31	30	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0																																																																																																											
RF_N															RF_N28				RF_N27				RF_N26				RF_N25				RF_N24				RF_N23				RF_N22				RF_N21				RF_N20				RF_N19				RF_N18				RF_N17				RF_N16				RF_N15				RF_N14				RF_N13				RF_N12				RF_N11				RF_N10				RF_N9				RF_N8				RF_N7				RF_N6				RF_N5				Fps				PCS				RF_N3				RF_PWDN				RF_N2				RF_N1				RF_N0			
																														1				0				0				0																																																																																																



### 2.6.1 RF\_N\_CNTR (RF\_N[28]-[14])

The RF N counter value is determined by three counter values that work in conjunction with four prescalers. This quadruple modulus prescaler architecture allows lower minimum continuous divide ratios than are possible with a dual modulus prescaler architecture. For the determination of the A, B, and C counter values, the fundamental relationships are shown below.

$$N = PC + 4B + A$$

$$C \geq \max \{A, B\} + 2$$

The A, B, and C values can be determined as follows:

$$C = N \text{ div } P$$

$$B = (N - CP) \text{ div } 4$$

$$A = (N - CP) \text{ mod } 4$$

#### N REGISTER FOR THE CELLULAR (8/9/12/13) PRESCALER OPERATING IN FRACTIONAL MODE

Divide Ratio	RF_N_CNTR [14:0]															
	C Word								B Word				A Word			
1-23	Divide Ratios Less than 24 are impossible since it is required that $C \geq 3$															
24-39	Some of these N values are Legal Divide Ratios, some are not															
40	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	
41	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	
...	.	.	.	.	.	.	.	.	.	.	.	0	.	.	.	
16383	1	1	1	1	1	1	1	1	1	1	1	1	0	1	1	

#### N REGISTER FOR THE PCS (16/17/20/21) PRESCALER OPERATING IN FRACTIONAL MODE

Divide Ratio	RF_N_CNTR [14:0]															
	C Word								B Word				A Word			
1-47	Divide Ratios Less than 48 are impossible since it is required that $C \geq 3$															
48-79	Some of these N values are Legal Divide Ratios, some are not															
80	0	0	0	0	0	0	0	0	1	0	1	0	0	0	0	
81	0	0	0	0	0	0	0	0	0	1	0	1	0	0	0	
...	.	.	.	.	.	.	.	.	.	.	.	0	.	.	.	
32767	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	

### 2.6.2 FRAC\_N (RF\_N[13]-[10])

These four bits, the fractional accumulator modulus numerator, set the fractional numerator values in the fraction.

Modulus Numerator	FRAC_N [3:0]			
0	0	0	0	0
1	0	0	0	1
2	0	0	1	0
.	.	.	.	.
14	1	1	1	0
15	1	1	1	1

### 2.6.3 FRAC\_D (RF\_N[9]-[6])

These four bits, the fractional accumulator modulus denominator, set the fractional denominator from 1/2 to 1/16 resolution.

Modulus Denominator	FRAC_D [3:0]			
1-8	Not Allowed			
9	1	0	0	1
10-14	.	.	.	.
15	1	1	1	1
16	0	0	0	0

#### MODULUS NUMERATOR (FRAC\_N) AND DENOMINATOR (FRAC\_D) PROGRAMMING

Fractional Numerator (FRAC_N) RF_N[13]-[10]	Fractional Denominator, (FRAC_D) RF_N[9]-[6]																
	1 0001	2 0010	3 0011	4 0100	5 0101	6 0110	7 0111	8 1000	9 1001	10 1010	11 1011	12 1100	13 1101	14 1110	15 1111	16 0000	
0=0000	Functions like an integer-N PLL as fractional component is set to 0.																
1=0001	*	*	*	*	*	*	*	*	1/9	1/10	1/11	1/12	1/13	1/14	1/15	1/16	
	(8/16)	(5/15)	(4/16)	(3/15)	(2/12)	(2/14)	(2/16)										
2=0010		*	*	*	*	*	*		2/9	2/10	2/11	2/12	2/13	2/14	2/15	2/16	
		(10/1	(8/16)	(6/15)	(4/12)	(4/14)	(4/16)										
		5)															
3=0011			*	*	*	*	*		3/9	3/10	3/11	3/12	3/13	3/14	3/15	3/16	
			(12/1	(9/15)	(6/12)	(6/14)	(6/16)										
			6)														
4=0100				*	*	*	*		4/9	4/10	4/11	4/12	4/13	4/14	4/15	4/16	
				(12/1	(8/12)	(8/14)	(8/16)										
				5)													
5=0101					*	*	*		5/9	5/10	5/11	5/12	5/13	5/14	5/15	5/16	
					(10/1	(10/1	(10/1										
					2)	4)	6)										
6=0110						*	*		6/9	6/10	6/11	6/12	6/13	6/14	6/15	6/16	
						(12/1	(12/1										
						4)	6)										
7=0111							*		7/9	7/10	7/11	7/12	7/13	7/14	7/15	7/16	
							(14/1										
							6)										
8=1000	FRAC_D values between 1 to 8 are not allowed.								8/9	8/10	8/11	8/12	8/13	8/14	8/15	8/16	
9=1001										9/10	9/11	9/12	9/13	9/14	9/15	9/16	
10=1010											10/1	10/1	10/1	10/1	10/1	10/16	
											1	2	3	4	5		
11=1011											11/1		11/1	11/1	11/1	11/16	
											2		3	4	5		
12=1100													12/1	12/1	12/1	12/16	
													3	4	5		
13=1101															13/1	13/1	13/16
															4	5	
14=1110															14/1		14/16
															5		
15=1111																	15/16

**Remark:** The \*(FRAC\_N / FRAC\_D) denotes that the fraction number can be represented by (FRAC\_N / FRAC\_D) as indicated in the parenthesis. For example, 1/2 can be represented by 8/16.

#### 2.6.4 FBPS (RF\_N[5])

This bit when set to one will bypass the delay line calculation used in the fractional circuitry. This will improve the phase noise while sacrificing performance on reference spurs. When the bit is set to zero, the delay line circuit is in effect to reduce reference spur.

#### 2.6.5 PCS (RF\_N[4])

This bit will determine whether the RF PLL should operate in PCS frequency range or cellular frequency range. When the

bit is set to one, the RF PLL will operate in the PCS mode and when it is set to zero, the cellular mode.

#### 2.6.6 RF\_PWDN (RF\_N[3])

This bit will asynchronously powerdown the RF PLL when set to one. For normal operation, it should be set to zero.

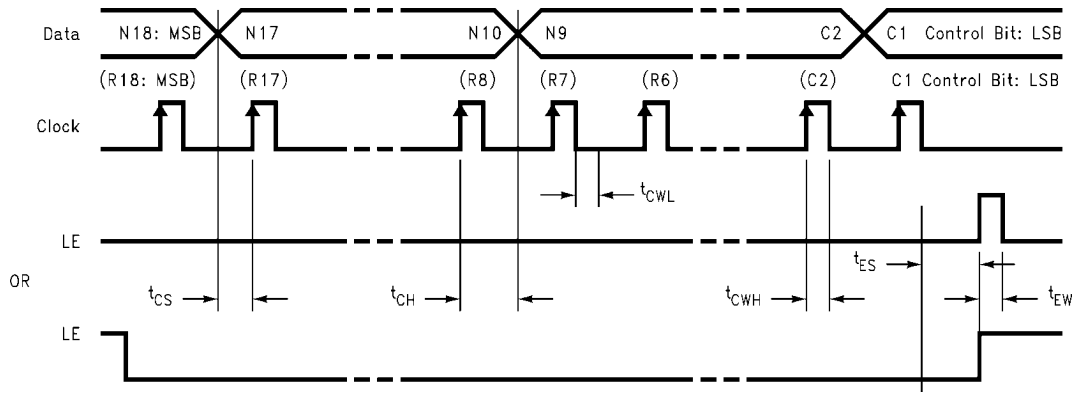
#### 2.6.7 Test (RF\_N[2]-[0])

These bits are the internal factory testing only. They should be set to zero for normal operation.

OBSOLETE



**SERIAL DATA INPUT TIMING**

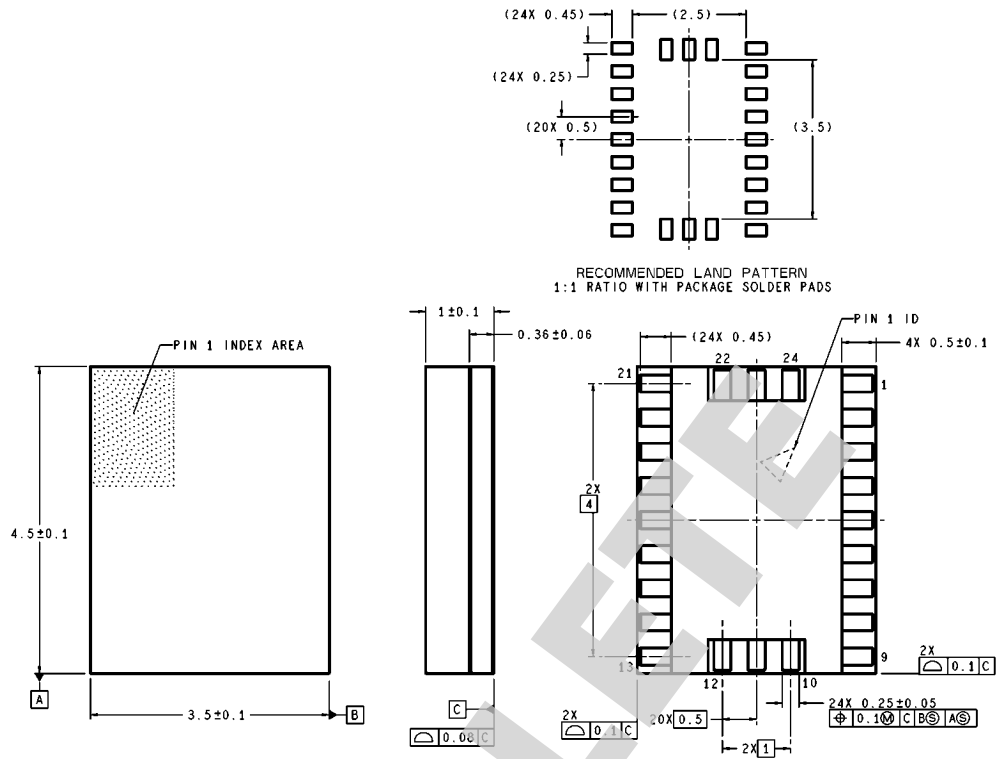


**Notes:** Parenthesis data indicates programmable reference divider data.  
 Data shifted into register on clock rising edge.  
 Data is shifted in MSB first.

**Test Conditions:** <sup>10136107</sup> The Serial Data Input Timing is tested using a symmetrical waveform around  $V_{CC}/2$ . The test waveform has an edge rate of 0.6 V/ns with amplitudes of 1.84V @  $V_{CC} = 2.3V$  and 4.4V @  $V_{CC} = 5.5V$ .

OBSOLETE

**Physical Dimensions** inches (millimeters) unless otherwise noted



DIMENSIONS ARE IN MILLIMETERS

SLB24A (Rev C)

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LVDS	<a href="http://www.national.com/lvds">www.national.com/lvds</a>	Packaging	<a href="http://www.national.com/packaging">www.national.com/packaging</a>
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LDOs	<a href="http://www.national.com/ldo">www.national.com/ldo</a>	Quality and Reliability	<a href="http://www.national.com/quality">www.national.com/quality</a>
LED Lighting	<a href="http://www.national.com/led">www.national.com/led</a>	Feedback/Support	<a href="http://www.national.com/feedback">www.national.com/feedback</a>
Voltage Reference	<a href="http://www.national.com/vref">www.national.com/vref</a>	Design Made Easy	<a href="http://www.national.com/easy">www.national.com/easy</a>
PowerWise® Solutions	<a href="http://www.national.com/powerwise">www.national.com/powerwise</a>	Solutions	<a href="http://www.national.com/solutions">www.national.com/solutions</a>
Serial Digital Interface (SDI)	<a href="http://www.national.com/sdi">www.national.com/sdi</a>	Mil/Aero	<a href="http://www.national.com/milaero">www.national.com/milaero</a>
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